

# CYPRESS SEMICONDUCTOR CORPORATION PRODUCT RELIABILITY REPORT

---

QUARTER 3, 1998



PERFORM PER THE REQUIREMENT OF 25-00008, RELIABILITY MONITOR PROGRAM SPECIFICATION

Ed Russell  
Reliability Manager

## STANDARD STRESS TEST DESCRIPTIONS

<u>TEST</u>	<u>DESCRIPTION</u>
HTOL	High Temp Op Life, 150°C, 5.75V
HTOL2	High Temp Op Life, 125°C, 5.75V
HTSSL	High Temp Steady State Life, 150°C, 5.75V
HTSSL2	High Temp Steady State Life, 125°C, 5.75V
DRET	Data Retention Test, Data Bake 165°C, Plastic
DRET2	Data Retention Test, Data Bake 250°C, Hermetic
PCT	Pressure Cooker Test, 121°C, 100%RH, No Bias
HAST	Hi-Accel Saturation Test, 140°C, 85%RH, 5.5V Bias
TC	Temp Cycle, 125°C to -40°C
TC2	Temp Cycle, 150°C to -65°C
HTS	High Temp Storage, 165°C, No Bias

WAFER FAB AREAS

<u>FAB #</u>	<u>LOCATION</u>
CA	San Jose, California
TX	Round Rock, Texas
MN	Bloomington, Minnesota
FR	MHS, France

ASSEMBLY LOCATION

<u>ID</u>	<u>COMPANY/LOCATION</u>
KOREA-A	Anam-Buchon/Korea
ASAT-B	Asat/Hongkong
USA-C	Cypress/USA
PHIL-D	Dynesem/Philippines
USA-E	Cypress-Minnesota/USA
INDNS-F	Astra/Indonesia
TAIWAN-G	ASE/Taiwan
KOREA-H	Hyundai/Korea
MALAY-J	ASE/Malaysia
THLAND-K	TMS/Thailand
KOREA-L	Anam-Seoul/Korea
PHIL-M	Anam/Philippines
USA-N	Express/USA
INDNS-O	Omedata/Indonesia
USA-P	Pantronix/USA
KOREA-Q	Anam-Bupyong/Korea
PHIL-R	Cypress/Philippines
USA-S	ATM/USA
TAIWAN-T	OSE/Taiwan
MALAY-U	Unisem/Malaysia
USA-V	Aplus/USA
USA-W	Toshiba/USA
ALPHA-X	Cypress Bangkok/Thailand
ALPHA-Y	Alphatech/Thailand
THLAND-Z	Hana/Thailand

## DESCRIPTION OF DATA TABLE COLUMN HEADINGS

<u>COLUMN HEADING</u>	<u>DESCRIPTION OF COLUMN CONTENTS</u>
Division	Cypress Manufacturing Division
Test	Common code for the stress performed. See table on previous page for detail.
Test Condition	Tem/humidity/bias condition for the stress. See table on previous for detail
Device ID	Cypress part number
Date Code	Week in which specific lot was marked/sealed/molded.
Lot Number	Manufacturing (assembly) lot number
Function	Generic product family at Cypress
Description	Brief description of device function
Technology	Fabrication process technology.
Process	Generic fabrication process
Pkg Material	Generic packaging material
Pkg Type	Common code for standard package configuration (PDIP=Plastic Dual-In-Line-Package).
Pkg Location	Country Location + Initial of assembly house (see table on prvious page for detail).
# Pins	Pin cont of package in which device is assembled.
Duration	Data Readpoint of stress. For Temp Cycle (TC) = Cycles; all other stresses=Hours.
# Test	Quantity of devices submitted to this stress/test.
# Failed	Quantity of devices failing at this specific readpoint.
Fail Mode	Failure analysis results from this test, if any.

**RELIABILITY DATA SUMMARY  
 (Q398)**

LONG TERM FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
	150C	125C	TOTAL <sup>1</sup> @ 150C		
FAMOS TOTAL	134,640	479,000	290,794	0	
FLASH TOTAL	0	0	0	0	
SRAM/LOGIC TOTAL	938,678	917,000	1,237,620	2	2 UNKNOWN
BICMOS TOTAL	0	180,000	58,680	0	
LFR TOTAL	1,073,318	1,576,000	1,587,094	2	2 UNKNOWN
EARLY FAILURE RATE SUMMARY					
PROCESS	UNITS TESTED			FAILED	FAILURE MODE
	150C	125C	TOTAL @ 150C		
FAMOS TOTAL	500	284	784	0	
FLASH TOTAL	0	0	0	0	
SRAM/LOGIC TOTAL	31,994	23,318	55,312	5	1 SHORTED METAL (BRIDGING), 2 NON VISUAL, 2 FA PENDING
BICMOS TOTAL	999	4,910	5,909	0	
EFR TOTAL	33,493	28,512	62,005	5	1 SHORTED METAL (BRIDGING), 2 NON VISUAL, 2 FA PENDING
HTSSL FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
	150C	125C	TOTAL <sup>1</sup> @ 150C		
FAMOS TOTAL	25,448	120,000	64,568	0	
FLASH TOTAL	0	0	0	0	
SRAM/LOGIC TOTAL	12,176	234,000	88,460	0	
BICMOS TOTAL	26,880	0	26,880	0	
HTSSL TOTAL	64,504	354,000	179,908	0	
TEMP CYCLE FAILURE RATE SUMMARY					
PROCESS	DEVICE CYCLE			FAILED	FAILURE MODE
	150C	125C	TOTAL <sup>1</sup> @ 150C		
FAMOS TOTAL	39,600	0	39,600	0	
FLASH TOTAL	0	0	0	0	
SRAM/LOGIC TOTAL	973,200	15,600	977,256	7	5 OPEN BOND LIFT/1 MIXED REJECT/1 TOPSIDE CRACK
BICMOS TOTAL	60,000	0	60,000	0	
TC TOTAL	1,072,800	15,600	1,076,856	7	5 OPEN BOND LIFT/1 MIXED REJECT/1 TOPSIDE CRACK

<sup>1</sup> Equivalent Total Device Hours/Cycles. Derating factors are used for lower stress condition.

**RELIABILITY DATA SUMMARY  
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HAST FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
	150C	125C	TOTAL <sup>1</sup> @ 150C		
FAMOS TOTAL	0	11,264	5,981	0	
FLASH TOTAL	0	0	0	0	
SRAM/LOGIC TOTAL	255,104	36,992	274,747	1	1 POLY FUSE DEFECT
BICMOS TOTAL	0	6,144	3,262	0	
HAST TOTAL	255,104	54,400	283,990	1	1POLY FUSE DEFECT
LTOL FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
FAMOS TOTAL	NO DATA			NO DATA	
FLASH TOTAL	NO DATA			NO DATA	
SRAM/LOGIC TOTAL	NO DATA			NO DATA	
BICMOS TOTAL	NO DATA			NO DATA	
LTOL TOTAL	NO DATA			NO DATA	
PCT FAILURE RATE SUMMARY					
PROCESS	DEVICE HOURS			FAILED	FAILURE MODE
FAMOS TOTAL	27,360			0	
FLASH TOTAL	0			0	
SRAM/LOGIC TOTAL	312,360			0	
BICMOS TOTAL	21,168			0	
PCT TOTAL	360,888			0	
DRET FAILURE RATE SUMMARY					
PROCESS	PLASTIC (165C)		HERMETIC(250C)		FAILURE MODE
	DHR	REJ	DHR	REJ	
FAMOS TOTAL	83,904	0	0	0	
FLASH TOTAL	0	0	0	0	
SRAM/LOGIC TOTAL	162,000	0	0	0	
BICMOS	76,000	0	0	0	
DRET TOTAL	321,904	0	0	0	

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Technology	Test	Test Condition	sion	tion	Divi- Device	Func- tion	Eval#	D/C	Lot No	Assembly Description	cess	Loc	Pro- type	Wfr Loc	Pkg Pin	Assy tion	No Test	Dura Fail	Qty Fail	Qty Mode
BICMOS-SM1	DRET	165C/NO BIAS	DCD	CHNL	CY7B991-JC		M83027	9818	219803361	PSCB	BICMOS	TX	PLCC	ALPHA-X	32	168 1000	76 76	0 0		
	HAST	130/3.63V	DCD	CHNL	CY7B9514V-AC		98051	9823	619803937	SONET/SHD	BICMOS	TX	TQFP	CSPI-R	100	128	48	0		
	HTOL	150C/4.8V	DCD	CHNL	CY7B9514V-AC		98051	9823	619803937	SONET/SHD	BICMOS	TX	TQFP	CSPI-R	100	48	500	0		
									619805327	SONET/SHD	BICMOS	TX	TQFP	CSPI-R	100	48	499	0		
	HTOL2	125C/4.8V	DCD	CHNL	CY7B9514V-AC		98051	9823	619803937	SONET/SHD	BICMOS	TX	TQFP	CSPI-R	100	80 500	120 120	0 0		
									619805327	SONET/SHD	BICMOS	TX	TQFP	CSPI-R	100	80 500	120 120	0 0		
					CY7B991-VC		97501	9819	219803586L	PSCB	BICMOS	TX	PLCC	ALPHA-X	32	48 48 80 500	353 647 120 120	0 0 0 0		
							98293	9827	219804875L	PSCB	BICMOS	TX	PLCC	ALPHA-X	32	48 48	450 600	0 0		
		125C/5.75V	DCD	CHNL	CY7B991-JC		98221	9822	219803965	PSCB	BICMOS	TX	PLCC	ALPHA-X	32	96 96	430 570	0 0		
									219803966	PSCB	BICMOS	TX	PLCC	ALPHA-X	32	96 96	140 860	0 0		
							M83010	9818	219803361	PSCB	BICMOS	TX	PLCC	ALPHA-X	32	96 96	120 380	0 0		

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode					
BICMOS-SM1	HTSSL	150C/3.63V	DCD	CHNL	CY7B9514V-AC	98051	9823	619803937	SONET/SHD	BiCMOS	TX	TQFP	CSPI-R	100	80	80	0						
								619805327	SONET/SHD	BiCMOS	TX	TQFP	CSPI-R	100	80	80	0						
	PCT	121C/100%RH	DCD	CHNL	CY7B9514V-AC	98051	9823	619803937	SONET/SHD	BiCMOS	TX	TQFP	CSPI-R	100	168	50	0						
					CY7B991-JC	M83024	9818	219803361	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	168	76	0						
	TC2	-65C TO 150C	DCD	CHNL	CY7B9514V-AC	98051	9823	619803937	SONET/SHD	BiCMOS	TX	TQFP	CSPI-R	100	300	50	0						
								619807608	SONET/SHD	BiCMOS	TX	TQFP	CSPI-R	100	300	55	0						
								CY7B991-JC	M83026	9818	219803361	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	300	45	0			
					CY7B991-VC	97501	9819	219803586L	PSCB	BiCMOS	TX	PLCC	ALPHA-X	32	300	50	0						



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Technology	Test	Test Condition	tion	tion	Divi- Device	Func- tion	Eval#	D/C	Lot No	Assembly Description	cess	Loc	Pro- type	Wfr Loc	Pkg Pin	Assy tion	Test	No Fail	Dura Fail	Qty Fail	Qty Mode
FAMOS-E3	DRET	165C/NO BIAS	PLD	37K	CY37256VP160-AC		98376	9823	619806102	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	168 552	76 76	0 0			
								9830	619808070	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	168 552	76 76	0 0			
	HAST	130C/5.5V	PLD	37K	CY37256VP160-AC		98376	9823	619806102	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	128	43	0	3	Thermal	EOS
								9830	619808070	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	128	45	0			
	HTOL	150C/5.75V	PLD	37K	CY37256VP160-AC		98376	9823	619806102	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	48 80 500	250 116 88	0 0 0			
								9830	619808070	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	48 48 80 500	50 200 140 140	0 0 0 0			
	HTSSL	150C/5.5V	PLD	37K	CY37256VP160-AC		98376	9823	619806102	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	80 168	76 76	0 0			
								9830	619808070	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	80 168	76 75	0 0	1	Latch-up	Induced Overst
	LTOL	-30C/6.50V	PLD	37K	CY37256VP160-AC		98376	9823	619806102	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	230 500 750	45 45 45	0 0 0			
	PCT	121C/100%RH	PLD	37K	CY37256VP160-AC		98376	9823	619806102 288	256 MCEL-3V CMOS		TW	TQFP	KOREA-Q	160	168	50	0			

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FAMOS-E3	PCT	121C/100%RH	PLD	37K	CY37256VP160-AC	98376	9830	619808070	256 MCEL-3V CMOS	TW	TQFP	KOREA-Q	160	168 288	45 45	0 0		
	TC2	-65C TO 150C	PLD	37K	CY37256VP160-AC	98376	9823	619806102	256 MCEL-3V CMOS	TW	TQFP	KOREA-Q	160	300	50	0		
							9830	619808070	256 MCEL-3V CMOS	TW	TQFP	KOREA-Q	160	300	50	0		

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
FAMOS-P20	HTOL	150C/5.75V	PLD	MAX	CY7C341-RMB	97453	9743	349705389	REPROG.PAL	CMOS	TX	WPGA	PHIL-M	84	184	10	0	
																	184	40
					CY7C344-HMB	97457	9742	349705317	REPROG.PAL	CMOS	TX	CERQ	PHIL-M	28	184	50	0	
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	HTOL2	125C/5.75V	PLD	MAX	CY7C341-JC	M82035	9814	619803505	REPROG.PAL	CMOS	TX	PLCC	KOREA-A	84	500	120	0	
															2000	120	0	
						M82038	9814	619803505	REPROG.PAL	CMOS	TX	PLCC	KOREA-A	84	96	284	0	
-----																		
	HTSSL2	125C/5.5V	PLD	MAX	CY7C341-JC	M82036	9814	619803505	REPROG.PAL	CMOS	TX	PLCC	KOREA-A	84	96	120	0	
															500	120	0	
-----																		
	TC2	-65C TO 150C	PLD	MAX	CY7C341-RMB	97453	9743	349705389	REPROG.PAL	CMOS	TX	WPGA	PHIL-M	84	100	50	0	
					CY7C344-HMB	97457	9742	349705317	REPROG.PAL	CMOS	TX	CERQ	PHIL-M	28	100	46	0	
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FAMOS-P26	HTOL2	125C/5.75V	MPD	PROM	CY27C010-PC	M82050	9747	619709651	128K x 8	CMOS	TX	PDIP	KOREA-H	32	500	120	0	
															1000	120	0	
															2000	119	0	
	HTSSL2	125C/5.5V	MPD	PROM	CY27C010-PC	M82021	9747	619709651	128K x 8	CMOS	TX	PDIP	KOREA-H	32	96	120	0	
															500	120	0	

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-C2AN	DRET	165C/NO BIAS	DCD	VME	VIC068A-BC	M83031	9821	349800804	VME INTERF.	CMOS	MN	PPGA	PHIL-M	144	168 1000	80 80	0 0	
	PCT	121C/100%RH	DCD	VME	VIC068A-BC	M83029	9821	349800804	VME INTERF.	CMOS	MN	PPGA	PHIL-M	144	168	80	0	
	TC2	-65C TO 150C	DCD	VME	VIC068A-BC	M83030	9821	349800804	VME INTERF.	CMOS	MN	PPGA	PHIL-M	144	300	50	0	

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Technology	Test	Test Condition	Division	Function	Device	Eval#	Assembly D/C Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-L20	DRET	165C/NO BIAS	DCD	VME	CY7C611A-NC	M83003	9818 619804439	RISC CONTRL	CMOS	TX	PQFP	HK-B	160	168 1000	82 82	0 0	
	TC	-40C TO 125C	DCD	VME	CY7C611A-NC	M83004	9818 619804439	RISC CONTRL	CMOS	TX	PQFP	HK-B	160	300	52	0	

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-L27	HTOL2	125C/5.75V	DCD	CHNL	CY7C955-NI	M83007	9729	619704922	TRANSCEIVER	CMOS	MN	PQFP	KOREA-L	128	96	273	1	1 Shorted Metal (Bridging)
		125C/6.5V	DCD	CHNL	CY7C955-NC	98319	9833	619808961	TRANSCEIVER	CMOS	TX	PQFP	KOREA-L	128	48 48	241 806	0 0	
	PCT	121C/100%RH	DCD	CHNL	CY7C955-NI	M83034	9732	619705642	TRANSCEIVER	CMOS	MN	PQFP	KOREA-L	128	168	80	0	
	TC2	-65C TO 150C	DCD	CHNL	CY7C955-NI	M83036	9732	619705642	TRANSCEIVER	CMOS	MN	PQFP	KOREA-L	128	300	50	0	

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode	
SRAM/LOGIC-L28	HAST	140C/3.63V	CPD	TTECH	CY22751PVC	M82055	9804	619800214	CLOCK SYN.	CMOS	MN	SSOP	CSPI-R	48	128	11	0		
															128	69	0		
		140C/5.5V	DCD	PCLOG	CY82C693-NC	98209	9828	619807947	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	128	45	0		
								619807948	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	128	45	0		
	HTOL	150C/5.75V	CPD	TTECH	CY2291SC	98195	9823	34980844/7	CLOCK SYN.	CMOS	TX	SOIC	PHIL-M	20	48	149	0		
															48	209	0		
			DCD	PCLOG	CY82C693-NC	98209	9828	619807947	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	48	168	0		
															80	78	0		
								619807948	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	48	168	0		
															80	78	0		
								9829	619808385	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	48	167	0	
	HTS	165C/NO BIAS	DCD	PCLOG	CY82C693-NC	98209	9828	619807948	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	336	48	0		
															1000	48	0		
	HTSSL	150C/5.5V	DCD	PCLOG	CY82C693-NC	98209	9828	619807948	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	80	73	0		
															168	72	0		
	LTOL	-30C/5.75V	CPD	FCT	CY74FCT543TSOC	98209	9822	619805959/	BUS SWITCH	CMOS	TX	SOIC	CSPI-R	24	500	45	0		



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Technology	Test	Test Condition	tion	tion	Divi- Func- Device	Eval#	D/C Lot No	Assembly Description	cess	Loc	Pro- type	Wfr Loc	Pkg Pin	Assy tion	Test	No Fail	Dura Fail	Qty Fail	Qty Mode
SRAM/LOGIC-L28	PCT	121C/100%RH	CPD	TTECH	CY22751PVC	M83017	9804 619800309	CLOCK SYN.	CMOS	MN	SSOP	CSPI-R	48	168	78	0			
			DCD	PCLOG	CY82C693-NC	98209	9828 619807948	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	168	48	0			
	TC2	-65C TO 150C	DCD	PCLOG	CY82C693-NC	98209	9828 619807947	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	300	47	0			
							619807948	PC CHIPSET	CMOS	TX	PQFP	MALAY-J	208	300	48	0			

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-L31	HAST	140C/3.63	CPD	FCT	CY74FCT163LD952	98298	-	619807278	16 BIT REG.	CMOS	MN	TSSO	CSPI-R	56	128	45	0	
		140C/3.63V	CPD	FCT	CY74FCT163LD827	98133	9810	619802795	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	128	44	0	
								619802795S	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	128	46	0	
															128	46	0	
	HTOL	150C/3.8V	CPD	FCT	CY74FCT163LD827	98133	9810	619802795	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	24	116	0	
															80	116	0	
															500	116	0	
								619802795S	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	24	116	0	
															24	116	0	
															80	116	0	
															80	116	0	
															500	116	0	
															500	116	0	
	HTS	165C/NO BIAS	CPD	FCT	CY74FCT163LD827	98133	9810	619802795	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	336	45	0	
								619802795S	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	336	44	0	
															336	47	0	
					CY74FCT163LD952	98298	-	619807278	16 BIT REG.	CMOS	MN	TSSO	CSPI-R	56	336	45	0	
															500	45	0	
	T/S	-55C TO 150C	CPD	FCT	CY74FCT163LD952	98298	-	619807278	16 BIT REG.	CMOS	MN	TSSO	CSPI-R	56	100	45	0	
															200	45	0	
	TC2	-65C TO 150C	CPD	FCT	CY74FCT163LD827	98133	9810	619802795	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	300	45	0	
								619802795S	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	300	44	0	

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Technology	Test	Test Condition	Division	Function	Device	Eval#	D/C	Assembly Lot No	Description	Process	Wfr Loc	Pkg type	Assy Loc	No Pin	Dura tion	Qty Test	Qty Fail	Fail Mode
SRAM/LOGIC-L31	TC2	-65C TO 150C	CPD	FCT	CY74FCT163LD827	98133	9810	619802795S	20 BIT BUF.	CMOS	MN	TSSO	TAIWAN-T	56	300	45	0	
					CY74FCT163LD952	98298	-	619807278	16 BIT REG.	CMOS	MN	TSSO	CSPI-R	56	300	45	0	
								619807279	16 BIT REG.	CMOS	MN	TSSO	CSPI-R	56	300	45	0	
								619807280	16 BIT REG.	CMOS	MN	TSSO	CSPI-R	56	300	45	0	

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SRAM/LOGIC-R28	HAST	130C/5.5	DCD	FIFO	CY7C4245-AC	M82060	9981	619804361	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	128	76	0		
		130C/5.5V	DCD	FIFO	CY7C4245-AC	M82059	9727	619704335	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	128	76	0		
		140C/5.5	MPD	COMDTY	CY7C1009-VC	MR83033	9802	619711572	256K x 4	CMOS	MN	SOJ	CSPI-R	32	128	80	0		
					CY7C109-VC	MR83093	9820	519805328	128K x 8	CMOS	MN	SOJ	INDNS-O	32	128	80	0		
		140C/5.5V	DCD	DPORT	CY7C136-JC	M83022	9811	519802844	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	128	80	0		
					FIFO	CY7C4245-AC	M83016	9750	619710221	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	128	76	0	
			MPD	COMDTY	CY7C109-ZC	97442	9735	349704960	128K x 8	CMOS	MN	TSOP	KOREA-GQ	32	128	48	0		
						98191	9817	619803751	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	128	45	0		
														128	47	0			
								619803752	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	128	46	0		
														128	46	0			
								619803753	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	128	45	0		
														128	48	0			
					CY7C188-VC	MR83028	9821	619805225	32K x 9	CMOS	MN	SOJ	CSPI-R	32	128	80	0		
					CY7C199-VC	98210	-	619805353	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	128	50	0		
								619805353L	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	128	50	0		
														128	50	0			
					CY7C199-ZC	98301	9821	619805266	32K x 8	CMOS	MN	TSOP	CSPI-R	28	128	45	0		
					CY7C199-ZI	MR82080	9808	619802112	32K x 8	CMOS	MN	TSOP	CSPI-R	28	128	76	0		

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SRAM/LOGIC-R28	HTOL	150C/5.5V	MPD	COMDTY	CY7C199-VC	98210	-	619805353	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	80	120	0			
								619805353L	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	80	120	80	120	0	
		150C/5.75V	MPD	COMDTY	CY7C185-VC	98296	9836	619810123	SML/64K	CMOS	TX	SOJ	CSPI-R	28	48	1512	0			
					CY7C197-VC	98236	9827	519807749	256K x 1	CMOS	TX	SOJ	CSPI-R	24	48	1518	0			
	HTOL2	125C/		MPD	COMDTY	CY7C109-VC	MR83020	9820	519805328	128K x 8	CMOS	MN	SOJ	INDNS-O	32	96	406	0		
		125C/5.75V	DCD	DPORT	CY7C136-JC	M80121	9742	519713305	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	96	12	0	96	52	0
																		96	52	0
																		500	116	0
																		1000	116	0
																		2000	116	0
				MPD	COMDTY	CY7C1009-VC	MR83001	9802	619711572	256K x 4	CMOS	MN	SOJ	CSPI-R	32	96	477	0		
				MPD	COMDTY	CY7C188-VC	MR83003	9821	619805225	32K x 9	CMOS	MN	SOJ	CSPI-R	32	96	377	0		
	125C/5.7V	DCD	DPORT	CY7C136-JC	M83005	9811	519802844	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	96	143	0	96	357	0	

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SRAM/LOGIC-R28	HTS	165C/NO BIAS	MPD	COMDTY	CY7C109-ZC	98191	9817	619803751	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	336	45	0			
					CY7C199-VC	98210	-	619805353	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	336 500	50 44	0 0			
								619805353L	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	336 336 500 500	50 50 36 44	0 0 0 0			
	HTSSL2	125C/5.5V	DCD	DPORT	CY7C136-JC	M82015	9704	349700386	2K x 8 DP	CMOS	MN	PLCC	PHIL-M	52	96 500	120 120	0 0			
PCT	121C/100%RH		DCD	DPORT	CY7C136-JC	M83020	9811	519802844	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	168	80	0			
					MPD	COMDTY	CY7C109-VC	MR83091	9820	519805328	128K x 8	CMOS	MN	SOJ	INDNS-O	32	168	80	0	
							CY7C185-VC	98296	9828	619807754	SML/64K	CMOS	TX	SOJ	CSPI-R	28	168	50	0	
		CY7C188-VC	MR83029	9821	619805225	32K x 9	CMOS	MN	SOJ	CSPI-R	32	168	70	0						
		CY7C197-VC	98236	9827	519807749	256K x 1	CMOS	TX	SOJ	CSPI-R	24	168	48	0						
T/S		-55C TO 150C	MPD	COMDTY	CY7C109-ZC	98191	9817	619803751	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	100 200	45 45	0 0			
TC2		-65C TO 150C	DCD	DPORT	CY7C136-JC	M83021	9811	519802844	2K x 8 DP	CMOS	MN	PLCC	INDNS-O	52	300	50	0			
					FIFO	CY7C4245-AC	M83008	9750	619710221	4Kx18 FIFO	CMOS	MN	TQFP	KOREA-Q	64	300	48	0		

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SRAM/LOGIC-R28	TC2	-65C TO 150C	MPD	COMDTY	CY7C1009-VC	MR82063	9807	619711668	256K x 4	CMOS	MN	SOJ	CSPI-R	32	300	43	5	5 Open- Bond Lift (Die)
						MR83035	9802	619711572	256K x 4	CMOS	MN	SOJ	CSPI-R	32	300	50	0	
					CY7C109-ZC	97442	9735	349704960	128K x 8	CMOS	MN	TSOP	KOREA-GQ	32	300	48	0	
								349704961	128K x 8	CMOS	MN	TSOP	KOREA-GQ	32	300	48	0	
								349704962	128K x 8	CMOS	MN	TSOP	KOREA-GQ	32	300	48	1	1 Mixed Reject
					98191	9817	619803751	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	300	45	0		
							619803752	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	300	45	0		
							619803753	128K x 8	CMOS	MN	TSOP	PHIL-GW	32	300	45	0		
					CY7C185-VC	98296	9828	619807754	SML/64K	CMOS	TX	SOJ	CSPI-R	28	300	48	0	
					CY7C199-VC	98210	-	619805353	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	300	50	0	
								619805353L	32K x 8	CMOS	MN	SOJ	PHIL-GW	28	300	50	0	
					CY7C199-ZI	MR83067	9819	619805260	32K x 8	CMOS	MN	TSOP	CSPI-R	28	300	50	0	

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SRAM/LOGIC-R3	HAST	140C/5.5V	MPD	COMDTY	CY7C1020-VC	98222	9801	619711135	32K x16	CMOS	MN	SOJ	CSPI-R	44	128	45	0	
					CY7C199-VC	MR83082	9816	619804270	256K	CMOS	MN	SOJ	CSPI-R	28	128	80	0	
HTOL	150C/6.5V	DCD	FIFO	CY7C4265-JC	97415	9710	619700831S	16KX18 FIFO	CMOS	MN	PLCC	PHIL-M	68	48	428	0		
						9711	619700973S	16KX18 FIFO	CMOS	MN	PLCC	PHIL-M	68	48	363	1	1 Non Visual	
						97415	619707057S	32Kx9 FIFO	CMOS	MN	PLCC	KOREA-A	32	48	382	0		
						9819	219803518P	32Kx9 FIFO	CMOS	MN	PLCC	KOREA-A	32	48	863	0		
HTOL2	125C/5.75V	MPD	COMDTY	CY7C1021-ZSC	MR83044	9825	619806720	64K x16	CMOS	MN	TSOP	CSPI-R	44	96	530	0		
				CY7C199-VC	M80193	9802	619711953	256K	CMOS	MN	SOJ	CSPI-R	28	96	111	0	5 EOS	
													500	103	0			
													1000	103	1	1	Unknown Cause	
													2000	102	0			
HTS	165C/NO BIAS	MPD	COMDTY	CY7C1020-VC	98222	9801	619711135	32K x16	CMOS	MN	SOJ	CSPI-R	44	336	45	0		
HTSSL2	125C/5.5V	MPD	COMDTY	CY7C199-VC	M82005	9802	619711953	256K	CMOS	MN	SOJ	CSPI-R	28	96	108	0		
															500	108	0	
			SYNC	CY7C1031-JC	M82046	9804	519800339	64K x 18	CMOS	MN	PLCC	INDNS-O	52	96	120	0		
													500	120	0			
PCT	121C/100%RH	MPD	COMDTY	CY7C199-VC	MR83080	9816	619804270	256K	CMOS	MN	SOJ	CSPI-R	28	168	80	0		



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SRAM/LOGIC-R3	T/S	-55C TO 150C	MPD	COMDTY	CY7C1020-VC	98222	9801	619711135	32K x16	CMOS	MN	SOJ	CSPI-R	44	100 200	45 45	0 0	
	TC2	-65C TO 150C	MPD	COMDTY	CY7C1020-VC	98222	9801	619711135	32K x16	CMOS	MN	SOJ	CSPI-R	44	300	45	0	
								619711136	32K x16	CMOS	MN	SOJ	CSPI-R	44	300	45	0	
								9825 619806605	32K x16	CMOS	MN	SOJ	CSPI-R	44	300	45	0	
					CY7C1021-VC	MR83053	9817	619804496	64K x16	CMOS	MN	SOJ	CSPI-R	44	300	53	0	
					CY7C199-VC	MR83081	9816	619804270	256K	CMOS	MN	SOJ	CSPI-R	28	300	50	0	

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SRAM/LOGIC-R31	HAST	140C/3.3V	MPD	SYNC	CY7C1399-VC	MR82038	9742	619708394	32K x 8	CMOS	MN	SOJ	PHIL-M	28	128	26	0	
												128	58	0				
								619804105	32K x 8	CMOS	MN	SOJ	PHIL-M	28	128	80	0	
		140C/5.5V	MPD	SYNC	CY7C1399-ZC	98206	9823	349800821	32K x 8	CMOS	MN	TSOP	PHIL-M	28	128	45	0	
	349800822							32K x 8	CMOS	MN	TSOP	PHIL-M	28	128	45	0		
	349800823							32K x 8	CMOS	MN	TSOP	PHIL-M	28	128	45	0		
	HTOL	150C/5.75V	MPD	SYNC	CY7C1399-ZC	98206	9823	349800821	32K x 8	CMOS	MN	TSOP	PHIL-M	28	80	116	0	
349800822								32K x 8	CMOS	MN	TSOP	PHIL-M	28	80	116	0		
349800823								32K x 8	CMOS	MN	TSOP	PHIL-M	28	80	116	0		
	HTOL2	125C/3.65V	MPD	SYNC	CY7C1399-VC	MR82003	9742	619708394	32K x 8	CMOS	MN	SOJ	PHIL-M	28	96	493	0	
	HTS	165C/NO BIAS	MPD	SYNC	CY7C1399-ZC	98206	9823	349800821	32K x 8	CMOS	MN	TSOP	PHIL-M	28	336	45	0	
											500	40	0					
349800822								32K x 8	CMOS	MN	TSOP	PHIL-M	28	336	45	0		
								349800823	32K x 8	CMOS	MN	TSOP	PHIL-M	28	336	45	0	
													500	40	0			
	PCT	121C/100%RH	MPD	SYNC	CY7C1399-VC	MR82040	9742	619708394	32K x 8	CMOS	MN	SOJ	PHIL-M	28	168	80	0	
MR83074								9816	619804105	32K x 8	CMOS	MN	SOJ	PHIL-M	28	168	80	0

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SRAM/LOGIC-R31	TC2	-65C TO 150C	MPD	SYNC	CY7C1399-VC	MR82039	9742	619708394	32K x 8	CMOS	MN	SOJ	PHIL-M	28	300	50	0	
							9816	619804105	32K x 8	CMOS	MN	SOJ	PHIL-M	28	300	50	0	
						98206	9823	349800821	32K x 8	CMOS	MN	TSOP	PHIL-M	28	300	45	0	
								349800822	32K x 8	CMOS	MN	TSOP	PHIL-M	28	300	45	0	
						349800823	32K x 8	CMOS	MN	TSOP	PHIL-M	28	300	45	0			

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SRAM/LOGIC-R32	HAST	140C/5.5V	MPD	COMDTY	CY62128-SC	98154	9821	619805763	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	128	50	0																
								619805764L	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	128	50	0																
								619805765L	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	128	50	0																
					CY7C109-VC	98207	9815	519803680	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	128	44	0	1 Thermal EOS															
								519804082	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	128	45	0																
HTOL	150C/3.45V	MPD	SYNC	CY6157R202V0-ZC	98364	9828	619808086	256K/2M ROM	CMOS	MN	TSOP	KOREA-GQ	32	48	3956	1	***** FA IS PENDING *****																
								619808087	256K/2M ROM	CMOS	MN	TSOP	KOREA-GQ	32	48	2679	0																
								9830	619808759	256K/2M ROM	CMOS	MN	TSOP	KOREA-GQ	32	48	2892	0															
								98154	9821	619805763	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	80	120	500	120	0	0											
																							619805764L	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	80	120	0	
																							619805765L	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	80	120	0	
								98265	9827	619807408D	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	1233	0	0	0												
																						9828	619807508D	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	1190	0	
								HTOL2	125C/3.8V	MPD	COMDTY	CY62256V-ZC	MR82011	9807	619801398	32K x 8	CMOS	MN	TSOP	CSPI-G	28	96	484	0									
																MR83007	9807	619801398	32K x 8	CMOS	MN	TSOP	CSPI-G	28	96	500	0						
125C/5.75	MPD	COMDTY	CY62256-SNC	MR82012	9809	519802034	32K x 8									CMOS	CA	NSOI	INDNS-O	28	96	150	0	3 Test Program Revision									
								96	153	0																							

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SRAM/LOGIC-R32	HTOL2	125C/5.75	MPD	COMDTY	CY7C109-VC	MR83021	9825	519806900	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	96	239	0		
		125C/5.75V	MPD	COMDTY	CY62256V-NSC	MR83022	9803	519800428	32K x 8	CMOS	MN	NSOI	INDNS-O	28	96	453	0		
		125C/6.5V	MPD	COMDTY	CY7C109-VC	97438	9745	519712349D	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	96	742	0		
	9746					519712283D	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	96	648	0				
	9752					519714712d	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	96	849	0				
	HTS	165C/NO BIAS	MPD	COMDTY	CY62128-SC	98154	9821	619805763	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	336	50	0		
								619805764L	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	336	50	0		
								619805765L	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	336	50	0		
					CY7C109-VC	98207	9815	519803680	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	336	45	0		
				519804082		128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	336	45	0					
				519804109		128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	336	45	0					
PCT			121C/100%RH	MPD	COMDTY	CY62256-SNC	MR83097	9820	519805349	32K x 8	CMOS	CA	NSOI	INDNS-O	28	168	79	0	
									CY62256V-NSC	MR82076	9745	519712511	32K x 8	CMOS	MN	NSOI	INDNS-O	28	96
						CY62256V-ZC	MR83054	9803	499802341	32K x 8	CMOS	MN	NSOI	INDNS-O	28	168	80	0	
				MR82070	9807		619801398	32K x 8	CMOS	MN	TSOP	CSPI-G	28	168	80	0			
				MR83024	9807		619801398	32K x 8	CMOS	MN	TSOP	CSPI-G	28	96	80	0			

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SRAM/LOGIC-R32	PCT	121C/100%RH	MPD	COMDTY	CY7C1009-ZC	98192	-	619804698	128K x 8(5)	CMOS	MN	TSOP	PHIL-GW	32	168	45	0									
								619804698L	128K x 8(5)	CMOS	MN	TSOP	PHIL-GW	32	168 168	45 45	0 0									
	TC2	-65C TO 150C	MPD	COMDTY	CY62128-SC	98154	9821	619805763	128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	300	50	0									
619805764L								128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	300	50	0										
619805765L								128K x 8	CMOS	MN	SOIC	TAIWAN-G	32	300	50	0										
								CY62256V-NSC	MR82075	9745	519712511	32K x 8	CMOS	MN	NSOI	INDNS-O	28	300	50	0						
							MR83055														9803	499802341	32K x 8	CMOS	MN	NSOI
								CY62256V-ZC	MR82069	9807	619801398	32K x 8	CMOS	MN	TSOP	CSPI-G	28	300	50	0						
							MR83025														9807	619801398	32K x 8	CMOS	MN	TSOP
								CY7C1009-ZC	98192	-	619804698	128K x 8(5)	CMOS	MN	TSOP	PHIL-GW	32	300	45	0						
							619804698L														128K x 8(5)	CMOS	MN	TSOP	PHIL-GW	32
								CY7C109-VC	98207	9815	519803680	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	300	45	0						
			519804082	128K x 8(5)	CMOS	MN	SOJ														INDNS-O	32	300	45	0	
			519804109	128K x 8(5)	CMOS	MN	SOJ														INDNS-O	32	300	44	1	1 Topside Crack
					MR82045	9807	519801541	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	300	45	0										

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SRAM/LOGIC-R32D	HTOL	150C/3.80V	MPD	SYNC	CY7C1399-VC	97508	9732	619706098	32K x 8	CMOS	MN	SOJ	CSPI-R	28	48	1010	0	
		150C/5.75V	MPD	COMDTY	CY7C1599-VC	97508	9740	619707953	32K x 8(5)	CMOS	MN	SOJ	CSPI-R	28	48	998	1	EOS/1 Non Visual
							9746	619709540	32K x 8(5)	CMOS	MN	SOJ	CSPI-R	28	48	1534	0	
	HTSSL2	125C/5.5V	MPD	COMDTY	CY7C1049-VC	M82057	9747	619709647	512K x 8	CMOS	MN	SOJ	KOREA-L	36	96 500	120 120	0 0	

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SRAM/LOGIC-R33	TC2	-65C TO 150C	MPD	COMDTY	CY7C1021V33-VC	MR83015	9731	619705415	64K x16	CMOS	MN	SOJ	TAIWN-G	44	300	60	0	
						MR83016	9740	619707946	64K x16	CMOS	MN	SOJ	TAIWN-G	44	300	60	0	



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SRAM/LOGIC-R42	HTOL	150C/3.8V	MPD	COMDTY	CY62148V-SC	98112	9826	619806743	512K x 8	CMOS	MN	SOIC	TAIWAN-G	32	48	188	0	
		48														301	0	
		150C/5.75V	MPD	COMDTY	CY62148-SC	98111	9827	619807424	512K x 8	CMOS	MN	SOIC	TAIWAN-G	32	500	120	0	
	HTOL2	125C/5.75V	MPD	COMDTY	CY62148-SC	98111	9827	619807424	512K x 8	CMOS	MN	SOIC	TAIWAN-G	32	96	1595	0	
	PCT	121C/100%RH	MPD	COMDTY	CY62148-SC	98111	9827	619807424	512K x 8	CMOS	MN	SOIC	TAIWAN-G	32	168	48	0	
					CY62148V-SC	98112	9826	619806743	512K x 8	CMOS	MN	SOIC	TAIWAN-G	32	168	46	0	
	TC2	-65C TO 150C	MPD	COMDTY	CY62148-SC	98111	9827	619807424	512K x 8	CMOS	MN	SOIC	TAIWAN-G	32	300	48	0	
					CY62148V-SC	98112	9826	619806743	512K x 8	CMOS	MN	SOIC	TAIWAN-G	32	300	48	0	

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SRAM/LOGIC-R42D	HAST	130C/3.63V	MPD	SYNCHR	CY7C1350-AC	98231	9824	619805770	128K x 36	CMOS	MN	TQFP	CSPI-R	100	128 256	45 44	1 0	1 Poly Fuse Defect		
						98357		619808643	128K x 36	CMOS	MN	TQFP	CSPI-R	100	128	48	0			
					140C/	MPD	COMDTY	CY7C1021V33-ZSC	MR82050	9816	619803608	64K x16	CMOS	MN	TSOP	KOREA-H	44	128	79	0
HTOL	150C/3.8V		MPD	SYNCHR	CY7C1350-AC	98357	9824	619805770	128K x 36	CMOS	MN	TQFP	CSPI-R	100	48 80 500	750 393 390	0 1 0	1 Unknown Cause/1 EOS		
							9828	619807192	128K x 36	CMOS	MN	TQFP	CSPI-R	100	48 48 80 548	288 396 396 396	0 0 0 0			
							CY7C1352-AC	98357	9832	619809153	128K x 36	CMOS	MN	TQFP	CSPI-R	100	48	66	0	
HTOL2	125C/3.8V		MPD	COMDTY	CY7C1021V33-VC	98261	9833	619808408	64K x16	CMOS	MN	SOJ	CSPI-R	44	96 96	906 906	0 0			
								619808409	64K x16	CMOS	MN	SOJ	CSPI-R	44	96 96	950 950	0 0			
								619808410	64K x16	CMOS	MN	SOJ	CSPI-R	44	96 96	905 905	0 0			
								619808411	64K x16	CMOS	MN	SOJ	CSPI-R	44	96 96	923 923	0 0			
								619808412	64K x16	CMOS	MN	SOJ	CSPI-R	44	96 96	979 979	0 0			
								619808413	64K x16	CMOS	MN	SOJ	CSPI-R	44	96 96	962 963	0 0			
								619808414	64K x16	CMOS	MN	SOJ	CSPI-R	44	96 96	1040 1041	0 0			

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SRAM/LOGIC-R42D	HTOL2	125C/3.8V	MPD	COMDTY	CY7C1021V33-VC	98261	9833	619808415	64K x16	CMOS	MN	SOJ	CSPI-R	44	96	1081	0									
								619808416	64K x16	CMOS	MN	SOJ	CSPI-R	44	96	986	0									
				CY7C1021V33-ZSC	MR82047	9816	619803608	64K x16	CMOS	MN	TSOP	KOREA-H	44	96	494	0										
	HTS	165C/NO BIAS	MPD	SYNCHR	CY7C1350-AC	98231	9824	619805769	128K x 36	CMOS	MN	TQFP	CSPI-R	100	336	45	0									
PCT	121C/100%RH		MPD	COMDTY	CY7C1021V33-ZSC	MR82052	9816	619803608	64K x16	CMOS	MN	TSOP	KOREA-H	44	168	76	0									
								MR83085	9812	619802905	64K x16	CMOS	MN	TSOP	KOREA-H	44	168	80	0							
				SYNCHR	CY7C1352-AC	98357		619808642	128K x 36	CMOS	MN	TQFP	CSPI-R	100	168	45	0									
														288	45	0										
	T/S	-55C TO 150C	MPD	SYNCHR	CY7C1350-AC	98231	9824	619805769	128K x 36	CMOS	MN	TQFP	CSPI-R	100	100	45	0									
														200	45	0										
TC2	-65C TO 150C		MPD	COMDTY	CY7C1021V33-ZSC	MR82052	9816	619803608	64K x16	CMOS	MN	TSOP	KOREA-H	44	300	50	0									
								MR83086	9812	619802905	64K x16	CMOS	MN	TSOP	KOREA-H	44	300	50	0							
												SYNCHR	CY7C1350-AC	98231	9824	619805769	128K x 36	CMOS	MN	TQFP	CSPI-R	100	300	45	0	
																619805770	128K x 36	CMOS	MN	TQFP	CSPI-R	100	300	45	0	
																9828	619807192	128K x 36	CMOS	MN	TQFP	CSPI-R	100	300	45	0
								98357	9824	619805769	128K x 36	CMOS	MN	TQFP	CSPI-R	100	300	45	0							

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SRAM/LOGIC-R42D	TC2	-65C TO 150C	MPD	SYNCHR	CY7C1350-AC	98357	9824	619805770	128K x 36	CMOS	MN	TQFP	CSPI-R	100	300	45	0	
							9828	619807192	128K x 36	CMOS	MN	TQFP	CSPI-R	100	300	45	0	

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SRAM/LOGIC-R42HD	HAST	140C/5.5V	MPD	SYNC	CY7C1011-ZC	98313	9817	619804340	128K x 16	CMOS	MN	TSOP	KOREA-H	44	128	50	0		
	HTOL	150C/5.75	MPD	COMDTY	CY7C1020-ZSC	98077	9816	619803865	32K x16	CMOS	MN	TSOP	KOREA-H	44	48	500	0		
								619803866	32K x16	CMOS	MN	TSOP	KOREA-H	44	48	500	0		
							9817	619803867	32K x16	CMOS	MN	TSOP	KOREA-H	44	48	500	0		
		150C/5.75V	DCD	DPORT	CY7C038-AC	98368	9826	619806813	64K x 18 DP	CMOS	MN	TQFP	TAIWAN-G	100	48	289	0		
							9829	619808005	64K x 18 DP	CMOS	MN	TQFP	TAIWAN-G	100	48	1234	0		
			MPD	COMDTY	CY7C1009-VC	98382	9834	619809780	256K x 4	CMOS	MN	SOJ	CSPI-R	32	48	1000	1	***** FA IS PENDING *****	
								619809782	256K x 4	CMOS	MN	SOJ	CSPI-R	32	48	1000	0		
								619809783	256K x 4	CMOS	MN	SOJ	CSPI-R	32	48	1000	0		
					CY7C1020-ZSC	98077	9816	619803865	32K x16	CMOS	MN	TSOP	KOREA-H	44	80	120	0		
								619803866	32K x16	CMOS	MN	TSOP	KOREA-H	44	80	120	0		
							9817	619803867	32K x16	CMOS	MN	TSOP	KOREA-H	44	80	120	0		
					SYNC	CY7C1011-ZC	98313	9825	619806805	128K x 16	CMOS	MN	TSOP	KOREA-H	44	48	1021	0	
	HTOL2	125C/5.75V	MPD	COMDTY	CY7C1021-VC	98263	9825	619807027	64K x16	CMOS	MN	SOJ	CSPI-R	44	96	1545	0		
					SYNC	CY7C1011-ZC	98313	9825	619806805	128K x 16	CMOS	MN	TSOP	KOREA-H	44	96	452	0	
	HTS	165C/NO BIAS	MPD	SYNC	CY7C1011-ZC	98297	9829	619807660	128K x 16	CMOS	MN	TSOP	CSPI-R	44	336	49	0		

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SRAM/LOGIC-R42HD	PCT	121C/100%RH	DCD	DPORT	CY7C038-AC	98368	9824	619806221	64K x 18 DP	CMOS	MN	TQFP	TAIWAN-G	100	168	44	0		
			MPD	COMDTY	CY7C1020-ZSC	98077	9816	619803865	32K x16	CMOS	MN	TSOP	KOREA-H	44	96 168	45 45	0 0		
								619803866	32K x16	CMOS	MN	TSOP	KOREA-H	44	96	45	0		
							9817	619803867	32K x16	CMOS	MN	TSOP	KOREA-H	44	96	45	0		
					CY7C109-VC	MR83039	9806	519801396	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	168	80	0		
					SYNC	CY7C1011-ZC	98313	9817	619804340	128K x 16	CMOS	MN	TSOP	KOREA-H	44	168	50	0	
	T/S	-55C TO 150C	MPD	SYNC	CY7C1011-ZC	98297	9829	619807660	128K x 16	CMOS	MN	TSOP	CSPI-R	44	100 200	50 50	0 0		
	TC2	-65C TO 150C	DCD	DPORT	CY7C038-AC	98368	9824	619806221	64K x 18 DP	CMOS	MN	TQFP	TAIWAN-G	100	300	48	0		
			MPD	COMDTY	CY7C1020-ZSC	98077	9816	619803865	32K x16	CMOS	MN	TSOP	KOREA-H	44	300	45	0		
								619803866	32K x16	CMOS	MN	TSOP	KOREA-H	44	300	45	0		
							9817	619803867	32K x16	CMOS	MN	TSOP	KOREA-H	44	300	45	0		
					CY7C109-VC	MR83040	9806	519801396	128K x 8(5)	CMOS	MN	SOJ	INDNS-O	32	300	50	0		
					SYNC	CY7C1011-ZC	98297	9829	619807660	128K x 16	CMOS	MN	TSOP	CSPI-R	44	300	50	0	
								619807703	128K x 16	CMOS	MN	TSOP	CSPI-R	44	300	50	0		

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SRAM/LOGIC-R42HD	TC2	-65C TO 150C	MPD	SYNC	CY7C1011-ZC	98297	9829	619807756	128K x 16	CMOS	MN	TSOP	CSPI-R	44	300	50	0	
						98313	9817	619804340	128K x 16	CMOS	MN	TSOP	KOREA-H	44	300	50	0	